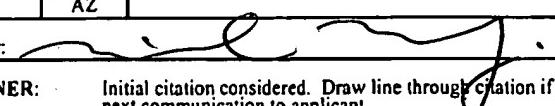


| FORM PTO-1449 (Modified) | | <p style="text-align: center;">U.S. Department of Commerce Patent and Trademark Office</p> <p style="text-align: center;">INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Seven Lines If Necessary)</p> <p style="text-align: center;">(37 CFR § 1.98(b))</p> | | Attorney Docket No.: COOL-00700 | | Serial No.: 10/669,495 | | |
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| | | | | Applicants: Thomas W. Kenny et al. | | | | |
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| EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | | | | | | | | |

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(Modified)

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U.S. Department of Commerce
Patent and Trademark Office

Attorney Docket No.: COOL-00700

Serial No.: 10/669,495

INFORMATION DISCLOSURE STATEMENT BY APPLICANT
(Use Several Sheets If Necessary)

Applicants: Thomas W. Kenny et al.

Filing Date: September 23, 2003

Group Art Unit: 3746

(37 CFR § 1.14(e))

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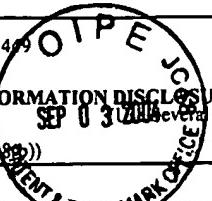
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

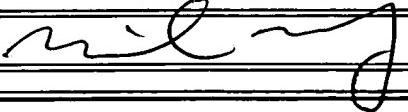
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| <p>Application Number: 10/669495</p> <p>Confirmation Number: 3987</p> <p>First Named Applicant: Thomas Kenny</p> <p>Attorney Docket Number:</p> <p>Search string: (3948316 or 5161089 or 5228502 or 5239443 or 5265670 or 5978220 or 5993750 or 6729383).pn.</p> | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| <p><u>Certification:</u> This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.</p> | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| <p>US Patent Documents</p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td>1</td><td>3948316</td><td>1976-04-06</td><td>Souriau</td><td></td><td></td><td></td><td></td></tr><tr><td>2</td><td>5161089</td><td>1992-11-03</td><td>Chu et al.</td><td></td><td></td><td></td><td></td></tr><tr><td>3</td><td>5228502</td><td>1993-07-20</td><td>Chu et al.</td><td></td><td></td><td></td><td></td></tr><tr><td>4</td><td>5239443</td><td>1993-08-24</td><td>Fahay et al.</td><td></td><td></td><td></td><td></td></tr><tr><td>5</td><td>5265670</td><td>1993-11-30</td><td>Zingher</td><td></td><td></td><td></td><td></td></tr><tr><td>6</td><td>5978220</td><td>1999-11-02</td><td>Frey et al.</td><td></td><td></td><td></td><td></td></tr><tr><td>7</td><td>5993750</td><td>1999-11-30</td><td>Ghosh et al.</td><td></td><td></td><td></td><td></td></tr><tr><td>8</td><td>6729383</td><td>2004-05-04</td><td>Cannell et al.</td><td>B1</td><td></td><td></td><td></td></tr></tbody></table> | | | | | | init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass | 1 | 3948316 | 1976-04-06 | Souriau | | | | | 2 | 5161089 | 1992-11-03 | Chu et al. | | | | | 3 | 5228502 | 1993-07-20 | Chu et al. | | | | | 4 | 5239443 | 1993-08-24 | Fahay et al. | | | | | 5 | 5265670 | 1993-11-30 | Zingher | | | | | 6 | 5978220 | 1999-11-02 | Frey et al. | | | | | 7 | 5993750 | 1999-11-30 | Ghosh et al. | | | | | 8 | 6729383 | 2004-05-04 | Cannell et al. | B1 | | | |
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| | | | | INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Separate Sheets If Necessary) | | Applicants: Thomas W. Kenny et al. | | | |
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| Application Number: | 10/669495  | | | | | | |
| Confirmation Number: | 3987 | | | | | | |
| First Named Applicant: | Thomas Kenny | | | | | | |
| Attorney Docket Number: | | | | | | | |
| Search string: | (3654988 or 3817321 or 3823572 or 3923426 or 3929154 or 4109707 or 4194559 or 4248295 or 4138996 or 4312012 or 4540115 or 4450472 or 4485429 or 4516632 or 4561040 or 4567505 or 4573067 or 4664181 or 4758926 or 4866570 or 4868712 or 4894709 or 4896719 or 4908112 or 4938280 or 5009760 or 5016138 or 5057908 or 5058627 or 5070040 or 5083194 or 5088005 or 5096388 or 5099311 or 5099910 or 5125451 or 5131233 or 5203401 or 5218515 or 5219278 or 5232047 or 5239200 or 5263251 or 5274920 or 5308429 or 5309319 or 5317805 or 5325265 or 5336062 or 5380956).pn. | | | | | | |
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Signature

| Examiner Name | Date |
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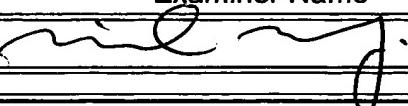
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| Application Number: | 10/669495  | | | | |
| Confirmation Number: | 3987 | | | | |
| First Named Applicant: | Thomas Kenny | | | | |
| Attorney Docket Number: | | | | | |
| Search string: | (5383340 or 5421943 or 5427174 or 5436793 or 5459099 or 5508234 or 5514832 or 5514906 or 5544696 or 5548605 or 5575929 or 5579828 or 5585069 or 5459099 or 5641400 or 5692558 or 5696405 or 5703536 or 5704416 or 5727618 or 5759014 or 5763951 or 5774779 or 5800690 or 5801442 or 5835345 or 5836750 or 5858188 or 5863708 or 5869004 or 5870823 or 5874795 or 5876655 or 5880017 or 5880524 or 5901037 or 5936192 or 5940270 or 5942093 or 5964092 or 5965001 or 5965813 or 5978220 or 5997713 or 5998240 or 6007309 or 6010316 or 6013164 or 6019882 or 6054034).pn. | | | | |
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Signature

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| Examiner Name | Date |
|  | 10-5-05 |



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

| Title of Invention | MICRO-FABRICATED ELECTROKINETIC PUMP WITH ON-FRIT ELECTRODE | | | | | | |
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| Application Number: | 10/669495 | | | | | | |
| Confirmation Number: | 3987 | | | | | | |
| First Named Applicant: | Thomas Kenny | | | | | | |
| Attorney Docket Number: | | | | | | | |
| Search string: | (6068752 or 6090251 or 6096656 or 6100541 or 6101715 or 6119729 or 6126723 or 6129145 or 6129260 or 6131650 or 6146103 or 6154363 or 6159353 or 6171067 or 6174675 or 6176962 or 6186660 or 6210986 or 6216343 or 6221226 or 6227809 or 6234240 or 6238538 or 6277257 or 6287440 or 6301109 or 6313992 or 6317326 or 6321791 or 6322753 or 6324058 or 6337794 or 6351384 or 6388317 or 6396706 or 6400012 or 6406605 or 6415860 or 6416642 or 6417060 or 6424531 or 6443222 or 6444461 or 6457515 or 6495015 or 6537437 or 6543521 or 6553253 or 6572749 or 6588498).pn. | | | | | | |
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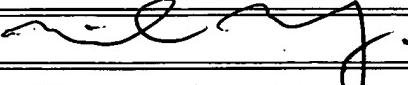
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Signature

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| Examiner Name | Date |
|  | CD-5-05 |



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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| Title of Invention | MICRO-FABRICATED ELECTROKINETIC PUMP WITH ON-FRIT ELECTRODE |
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Application Number: 10/669495



Confirmation Number: 3987

First Named Applicant: Thomas Kenny

Attorney Docket Number:

Search string: (6591625 or 6632655 or 20010016985 or
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or 20010046703 or 20010055714 or
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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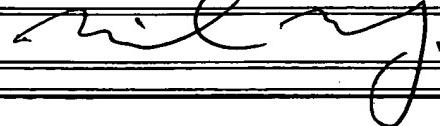
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Signature

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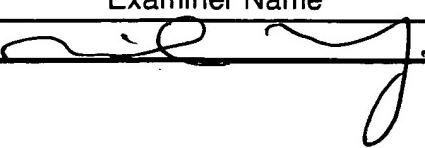
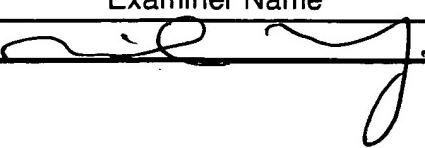
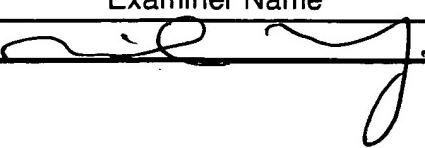
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

| Title of Invention | MICRO-FABRICATED ELECTROKINETIC PUMP WITH ON FRIT-ELECTRODE | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| Confirmation Number: | 3987 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| First Named Applicant: | Thomas Kenny | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Attorney Docket Number: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Art Unit: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Examiner: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| <p>Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.</p> | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| <h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td>1</td><td>1</td><td>0596062</td><td>1897-12-28</td><td>W. P. Firey</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>2273505</td><td>1942-02-17</td><td>R. R. Florian</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>4211208</td><td>1980-07-08</td><td>Lindner</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>6397932</td><td>2002-06-04</td><td>Calaman et al.</td><td>B1</td><td></td><td></td></tr></tbody></table> | | | | | | | | init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass | 1 | 1 | 0596062 | 1897-12-28 | W. P. Firey | | | | | 2 | 2273505 | 1942-02-17 | R. R. Florian | | | | | 3 | 4211208 | 1980-07-08 | Lindner | | | | | 4 | 6397932 | 2002-06-04 | Calaman et al. | B1 | | |
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| <h3>US Published Applications</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Published Applications</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Pub. No.</th><th>Date</th><th>Applicant</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>20020075645</td><td>2002-06-20</td><td>Kitano et al.</td><td>A1</td><td></td><td></td></tr></tbody></table> | | | | | | | | init | Cite.No. | Pub. No. | Date | Applicant | Kind | Class | Subclass | | 1 | 20020075645 | 2002-06-20 | Kitano et al. | A1 | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| <h3>Signature</h3> <table border="1"><tr><td>Examiner Name</td><td>Date</td></tr><tr><td></td><td>10-5-05</td></tr></table> | | | | | | | | Examiner Name | Date |  | 10-5-05 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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| First Named Applicant: | | Thomas Kenny | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| Examiner Name | Date |
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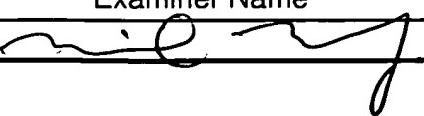
ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

| Title of Invention | MICRO-FABRICATED ELECTROKINETIC PUMP WITH ON-FRIT ELECTRODE | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| Application Number : | 10/669495 | |  | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Confirmation Number: | 3987 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| First Named Applicant: | Thomas Kenny | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Attorney Docket Number: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Art Unit: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Examiner: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Search string: | (5316077 or 6167948 or 6606251 or 20030062149).pn | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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|  | 10-5-05 |

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| First Named Applicant: | Thomas Kenny | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| | 6 | 6366467 | 2002-04-02 | Patel et al. | B1 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 7 | 6459581 | 2002-10-01 | Newton et al. | B1 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| <p>US Published Applications</p> <p>Note: Applicant is not required to submit a paper copy of cited US Published Applications</p> | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |

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| init | Cite.No. | Pub. No. | Date | Applicant | Kind | Class | Subclass |
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| mjk | 1 | 20020121105 | 2002-09-05 | McCarthy, Jr. et al. | A1 | | |
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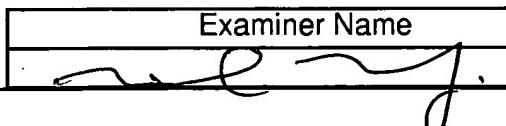
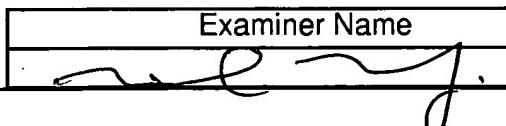
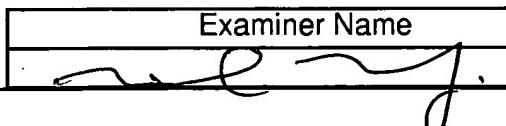
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| Examiner Name | Date |
|  | 10-5-05 |

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

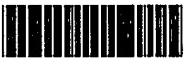
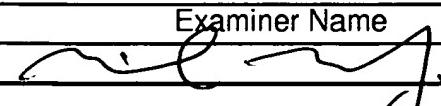
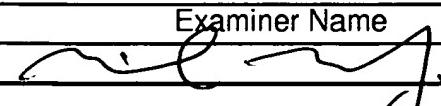
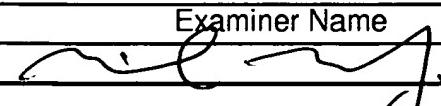
| Title of Invention | MICRO-FABRICATED ELECTROKINETIC PUMP WITH ON-FRIT ELECTRODE | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| Application Number : | 10/669495 | |  | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Confirmation Number: | 3987 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| First Named Applicant: | Thomas Kenny | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Attorney Docket Number: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Art Unit: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Examiner: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Search string: | (6438984 or 6581388 or 6587343).pn | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| <p><u>Certification:</u> This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.</p> | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| <h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td>nyk</td><td>1</td><td>6438984</td><td>2002-08-27</td><td>Novotny et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>2</td><td>6581388</td><td>2003-06-24</td><td>Novotny et al.</td><td>B2</td><td></td><td></td></tr><tr><td></td><td>3</td><td>6587343</td><td>2003-07-01</td><td>Novotny et al.</td><td>B2</td><td></td><td></td></tr></tbody></table> | | | | | | | | init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass | nyk | 1 | 6438984 | 2002-08-27 | Novotny et al. | B1 | | | | 2 | 6581388 | 2003-06-24 | Novotny et al. | B2 | | | | 3 | 6587343 | 2003-07-01 | Novotny et al. | B2 | | |
| init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| nyk | 1 | 6438984 | 2002-08-27 | Novotny et al. | B1 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 2 | 6581388 | 2003-06-24 | Novotny et al. | B2 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 3 | 6587343 | 2003-07-01 | Novotny et al. | B2 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| <p>Signature</p> <table border="1"><tr><td>Examiner Name</td><td>Date</td></tr><tr><td></td><td>10-5-05</td></tr></table> | | | | | | | | Examiner Name | Date |  | 10-5-05 | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Examiner Name | Date | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
|  | 10-5-05 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |

1-27-05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

| Title of Invention | MICRO-FABRICATED ELECTROKINETIC PUMP WITH ON-FRIT ELECTRODE | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| Application Number : | 10/669495 | |  | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Confirmation Number: | 3987 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| First Named Applicant: | Thomas Kenny | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Attorney Docket Number: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Art Unit: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Examiner: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Search string: | (2039593 or 4574876 or 6206022 or 6253835 or 6437981).pn | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| <h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td>MU</td><td>1</td><td>2039593</td><td>1936-05-05</td><td>T. N. Hubbuch et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>4574876</td><td>1986-03-11</td><td>Aid</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>6206022</td><td>2001-03-27</td><td>Tsai et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>4</td><td>6253835</td><td>2001-07-03</td><td>Chu et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>5</td><td>6437981</td><td>2002-08-20</td><td>Newton et al.</td><td>B1</td><td></td><td></td></tr></tbody></table> | | | | | | | | init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass | MU | 1 | 2039593 | 1936-05-05 | T. N. Hubbuch et al. | | | | | 2 | 4574876 | 1986-03-11 | Aid | | | | | 3 | 6206022 | 2001-03-27 | Tsai et al. | B1 | | | | 4 | 6253835 | 2001-07-03 | Chu et al. | B1 | | | | 5 | 6437981 | 2002-08-20 | Newton et al. | B1 | | |
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| | 3 | 6206022 | 2001-03-27 | Tsai et al. | B1 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| | 5 | 6437981 | 2002-08-20 | Newton et al. | B1 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| <p>Signature</p> <table border="1"><tr><td>Examiner Name</td><td>Date</td></tr><tr><td></td><td>10-5-05</td></tr></table> | | | | | | | | Examiner Name | Date |  | 10-5-05 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Examiner Name | Date | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| FORM PTO-1449 (Modified) | U.S. Department of Commerce Patent and Trademark Office | Attorney Docket No.: COOL-00700 | Serial No.: 10/669,495 |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary) (37 CFR § 1.98(b)) | | Applicants: Thomas W. Kenny et al. | |
| | | Filing Date: September 23, 2003 | Group Art Unit: 3746 |

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use Several Sheets If Necessary)

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| | | Document Number | Publication Date | Country / Patent Office | Class | Subclass | Translation | |
|----|----|-----------------|------------------|-------------------------|-------|----------|-------------|----|
| | | | | | | | Yes | No |
| ML | AA | 97212126.9 | 03/04/97 | CN | BO1D | 61/42 | | X |
| ML | AB | 2000-277540 | 10/06/00 | JP | HO1L | 21/50 | | X |

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Examiner:

Date Considered:

10-5-05

EXAMINER:

Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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|---|------|---|---------------------------------|------------------------|
| FORM PTO-1449 (Modified) | | U.S. Department of Commerce Patent and Trademark Office | Attorney Docket No.: COOL-00700 | Serial No.: 10/669,495 |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary) (37 CFR § 1.98(b)) | | Applicants: Thomas W. Kenny et al. | | |
| | | Filing Date: September 23, 2003 | Group Art Unit: 3746 | |
| OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication) | | | | |
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